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PATENT  
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March 20, 2002

Date

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant	: Tongbi Jiang	Attorney Docket No.	: 500182.01 (660073.774)
Serial No.	: 09/365,356	Group Art Unit	: 2813
Filed	: July 30, 1999	Examiner	: Nema O. Berezny
Title	: METHOD AND STRUCTURE FOR MANUFACTURING IMPROVED YIELD SEMICONDUCTOR PACKAGED DEVICES		

Box RCE  
Commissioner of Patents  
Washington, DC 20231

AMENDMENT

Sir:

Please amend the above-captioned patent application as follows:

In the Claims:

Please amend claims 1, 5-7, 9-11, 17-18, 38-40, and 42 as follows:

- Sub F1  
E1
1. (Twice Amended) A semiconductor device package, comprising:  
a semiconductor die having a first surface on which an integrated circuit and at least one electrically conductive bond pad are fabricated, the die having first and second pairs of opposed lateral edges;  
at least one electrically conductive external terminal;